

Film Capacitors

Metallized Polypropylene Film Capacitors (MKP)

 Series/Type:
 B32774 ... B32778

 Date:
 February 2017

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Metallized polypropylene film capacitors (MKP)

MKP DC link – high density series up to 480 μ F

Recommended applications

- Frequency converters
- Industrial and high-end power supplies
- Solar inverters

Climatic

- Max. operating temperature: 105 °C (case)
- Climatic category (IEC 60068-1): 40/105/56

Construction

- Dielectric: Polypropylene (MKP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

Features

- Capacitance values up to 480 uF
- High CV product, compact
- Good self-healing properties
- Over-voltage capability
- Low losses with high current capability
- High reliability
- Long useful life
- RoHS-compatible

Terminals

- Parallel wire leads, lead-free tinned
- 2-pin, 4-pin and 12-pin versions
- Standard lead lengths: 6 -1 mm

Marking

Manufacturer's logo and lot number, date code, rated capacitance (coded). capacitance tolerance (code letter) and rated DC voltage

Delivery mode

Bulk (untaped)





B32774 ... B32778

MKP DC link – high density series up to 480 μF

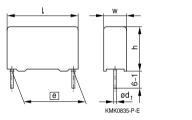
Dimensional drawings

Dimensions in mm

Number of wires	Lead spacing e ±0.4	Lead diameter $d_1 \pm 0.05$	Туре
2-pin	27.5	0.8	B32774D
2-pin	37.5	1.0	B32776E
2-pin	37.5	1.0	B32776T
4-pin	37.5	1.2	B32776G
4-pin	37.5	1.2	B32776T
4-pin	52.5	1.2	B32778T
4-pin	52.5	1.2	B32778G
12-pin	52.5	1.2	B32778J

Dimensional drawings 2-pin versions

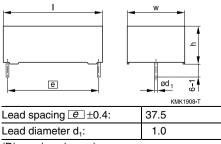
B32774D, B32776E



	B32774D	B32776E
Lead spacing $e \pm 0.4$: Lead diameter d ₁ :	27.5 0.8	37.5 1.0

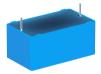
(Dimensions in mm)

B32776T (low profile)



(Dimensions in mm)







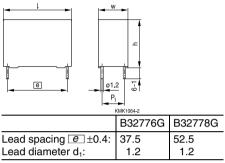


B32774 ... B32778

MKP DC link – high density series up to 480 μF

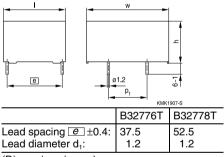
Dimensional drawings 4-pin versions

B32776G, B32778G



(Dimensions in mm)

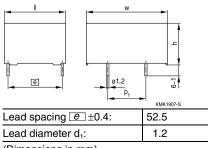
B32776T, B32778T (low profile)



(Dimensions in mm)

Dimensional drawing 12-pin version

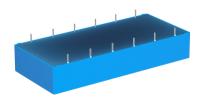
B32778J



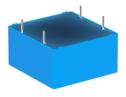
(Dimensions in mm)

Please read Cautions and warnings and

Important notes at the end of this document.









B32774 ... B32778

MKP DC link – high density series up to 480 μF

Overview of available types

Lead spacing	27.5 m	m			37.5 m	m				
Туре	B32774	4			B32776	6				
Page	7				8					
V _R (V DC)	450	800	1100	1300	450	575	800	900	1100	1300
C _R (μF)										
1.5										
2.0										
2.7										
3.0										
3.3										
3.5										
3.9										
5.0										
6.8										
7.0										
7.5										
8.0										
8.5										
9.0										
10										
12										
13										
14										
15										
16										
20										
22										
25										
30										
35										
40										
45										
50										
60										
65										





B32774 ... B32778

MKP DC link – high density series up to 480 μF

Lead spacin	g 52.5 mm					
Туре	B32778					
Page	11					
V _R (V DC)	450	575	800	900	1100	1300
C _R (μF)						
14						
20						
25						
27						
30						
35						
38						
40						
42						
45						
50						
55						
58						
60						
70						
75						
80						
90						
100						
110						
120						
130						
150						
170						
180						
200						
210						
270						
360						
480						



27.5

B32774

MKP DC link – high density series – up to 480 μF

Ordering codes and packing units (lead spacing 27.5 mm)

0 1)		D		1 2)			1 9	1 C	
$C_R^{1)}$	Max. dimensions	P ₁	Ordering code	RMS,max ²⁾	210	ESL _{typ} ³⁾	tan o	tan δ	pcs.
	$w \times h \times l$		(composition see	70 °C	70 °C	70 °C			MOQ
			below)	10 kHz	10 kHz	10 kHz	1 kHz	10 kHz	
μF	mm	mm		A	mΩ	nH	10 ⁻³	10 ⁻³	
$V_{R,70}$	° _C = 450 V DC, V _{op} ,	_{85 °C} =	450 V DC	-					
5.0	$11.0 \times 21.0 \times 31.5$		B32774D4505+000	5.0	21.1	19.0	1.2	10.7	2352
10.0	$15.0\times24.5\times31.5$	_	B32774D4106+000	8.0	10.9	24.0	1.2	11.0	1680
22.0	$22.0\times36.5\times31.5$	—	B32774D4226+000	14.5	5.4	30.0	1.3	12.1	784
$V_{R,70}$	$_{\rm C}$ = 800 V DC, V _{op} ,	_{85 °C} =	700 V DC						
3.0	$11.0 \times 21.0 \times 31.5$	_	B32774D8305+000	4.5	24.8	19.0	0.9	7.6	2352
5.0	$14.0 \times 24.5 \times 31.5$	_	B32774D8505+000	6.5	15.3	23.0	0.9	7.7	1848
12.0	$22.0\times36.5\times31.5$	_	B32774D8126+000	13.0	6.8	34.0	1.0	8.3	784
V _{R,70}	° _C = 1100 V DC, V _{op} ,	_{85 °C} =	920 V DC						
2.0	$12.5 \times 21.5 \times 31.5$	-	B32774D0205+000	4.5	26.3	19.0	0.7	5.3	2100
3.3	$18.0\times27.5\times31.5$	_	B32774D0335+000	7.0	16.2	22.0	0.7	5.4	1428
5.0	$19.0\times30.0\times31.5$	_	B32774D0505+000	9.0	10.9	27.0	0.7	5.5	896
7.0	$22.0\times36.5\times31.5$	_	B32774D0705+000	12.0	8.1	30.0	0.7	5.8	784
$V_{R,70}$	$_{\rm C}$ = 1300 V DC, V _{op} ,	_{85 °C} =	1100 V DC						
1.5	$12.5 \times 21.5 \times 31.5$		B32774D1155K000	4.4	31.3	20.0	0.6	4.8	2100
3.0	$18.0\times27.5\times31.5$	_	B32774D1305K000	7.0	16.0	24.0	0.6	4.9	1428
5.0	$22.0\times36.5\times31.5$	_	B32774D1505K000	10.5	9.8	33.0	0.7	5.1	784

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Intermediate capacitance values are available on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $J = \pm 5\%$ K = $\pm 10\%$

1) Capacitance value measured at 1 kHz

²⁾ Max ripple current I_{RMS} at 70 °C, 10 kHz for $\Delta T \le 20$ °C at $\Delta ESR_{typ} \le \pm 5\%$



B32776

MKP DC link – high density series – up to 480 μF

Ordering codes and packing units (lead spacing 37.5 mm)

$C_R^{1)}$	Max. dimensions	P ₁	Ordering code	I _{RMS,max} 2)	ESR _{typ}	ESL _{typ} ³⁾	tan δ	tan δ	pcs.
	w × h × l		(composition see	70 °C	70 °C	70 °C			MOQ
			below)	10 kHz	10 kHz	10 kHz	1 kHz	10 kHz	
μF	mm	mm	,	A	mΩ	nH	10 ⁻³	10 ⁻³	
$V_{R,70}$	$_{\rm C} = 450 \text{ V DC}, \text{ V}_{\rm op},$	_{85 °C} =	450 V DC						
12	24.0 imes 15.0 imes 41.5	_	B32776T4126K000	7.0	17.1	19.0	2.2	21.0	1040
16	$24.0\times19.0\times41.5$	-	B32776T4166K000	8.0	13.0	18.0	2.3	21.2	780
30	$20.0\times 39.5\times 41.5$	10.2	B32776G4306+000	14.0	7.0	11.0	2.3	21.3	640
30	$20.0\times 39.5\times 41.5$	-	B32776E4306+000	14.0	7.3	28.0	2.4	22.3	640
35	$28.0\times37.0\times42.0$	10.2	B32776G4356+000	16.5	6.0	10.0	2.3	21.4	440
35	$28.0\times37.0\times42.0$	-	B32776E4356+000	16.0	6.4	24.0	2.4	22.6	440
40	$28.0\times37.0\times42.0$	10.2	B32776G4406+000	17.5	5.3	11.0	2.3	21.4	440
40	$28.0\times37.0\times42.0$	-	B32776E4406+000	17.0	5.6	26.0	2.4	22.7	440
40	$43.0 \times 22.0 \times 41.5$	20.3	B32776T4406K000	17.0	5.2	13.0	2.3	21.2	280
50	$28.0\times42.5\times41.5$	10.2	B32776G4506+000	20.0	4.3	12.0	2.3	21.7	440
50	$28.0\times42.5\times41.5$	-	B32776E4506+000	19.0	4.7	30.0	2.5	23.8	440
60	$30.0 \times 45.0 \times 42.0$	20.3	B32776G4606+000	23.5	3.6	14.0	2.4	22.3	400
60	$30.0 \times 45.0 \times 42.0$	-	B32776E4606+000	22.0	4.0	32.0	2.5	24.2	400
65	$33.0 \times 48.0 \times 42.0$	20.3	B32776G4656+000	25.5	3.3	14.0	2.3	22.2	180
$V_{R,70}$	$_{\rm C} = 575 \text{ V DC}, \text{ V}_{\rm op},$	_{85 °C} =	500 V DC						
8.5	$24.0\times15.0\times41.5$	-	B32776T5855+000	6.5	19.9	19.0	1.9	17.2	1040
12	$24.0\times19.0\times41.5$	-	B32776T5126K000	8.0	14.4	18.0	1.9	17.4	780
25	$20.0\times39.5\times41.5$	10.2	B32776G5256K000	14.0	7.0	12.0	1.9	17.5	640
25	$20.0\times 39.5\times 41.5$	-	B32776E5256K000	13.5	7.4	28.0	2.0	18.3	640
30	$28.0\times37.0\times42.0$	10.2	B32776G5306K000	16.5	5.8	11.0	1.9	17.6	440
30	$28.0\times37.0\times42.0$	-	B32776E5306K000	16.5	6.1	26.0	2.0	18.5	440
30	$43.0 \times 22.0 \times 41.5$	20.3	B32776T5306K000	16.5	5.8	13.0	1.9	17.3	280
35	$28.0\times42.5\times41.5$	10.2	B32776G5356+000	19.0	5.0	12.0	1.9	17.8	440
35	$28.0\times42.5\times41.5$	-	B32776E5356+000	18.0	5.3	29.0	2.0	19.0	440
45	$30.0 \times 45.0 \times 42.0$	20.3	B32776G5456K000	22.0	4.0	13.0	1.9	17.9	400
45	$30.0 \times 45.0 \times 42.0$	-	B32776E5456K000	21.0	4.4	32.0	2.1	19.7	400
50	$33.0\times48.0\times42.0$	20.3	B32776G5506K000	25.0	3.5	14.0	2.0	18.1	180

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Intermediate capacitance values are available on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $J = \pm 5\%$

K = ±10%

1) Capacitance value measured at 1 kHz

2) Max ripple current I_{RMS} at 70 °C, 10 kHz for $\Delta T \le 20$ °C at $\Delta ESR_{typ} \le \pm 5\%$



B32776

MKP DC link – high density series – up to 480 μF

Ordering codes and packing units (lead spacing 37.5 mm)

$C_B^{(1)}$	Max. dimensions	P ₁	Ordering code	I _{RMS,max} 2)	ESR _{tvp}	ESL _{typ} ³⁾	tan δ	tan δ	pcs.
	w × h × l		(composition see	70 °C	70 °℃	70 °Ĉ			MOQ
			below)	10 kHz	10 kHz	10 kHz	1 kHz	10 kHz	
μF	mm	mm		A	mΩ	nH	10-3	10-3	
	° _C = 800 V DC, V _{op}	85 °C =	700 V DC		1	1	-	<u> </u>	1
6.8		_	B32776T8685+000	6.0	22.1	18.0	1.7	15.1	1040
	$24.0 \times 19.0 \times 41.5$	_	B32776T8855+000	7.5	17.8	18.0	1.7	15.1	780
14	18.0 × 32.5 × 41.5	_	B32776E8146+000	10.0	11.5	23.0	1.8	16.3	720
15	$20.0 \times 39.5 \times 41.5$	10.2	B32776G8156+000	12.0	9.6	10.0	1.7	15.2	640
15	$20.0 \times 39.5 \times 41.5$	_	B32776E8156+000	11.5	10.3	24.0	1.7	15.7	640
20	$28.0 \times 37.0 \times 42.0$	10.2	B32776G8206+000	14.5	7.5	10.0	1.7	15.3	440
20	$28.0\times37.0\times42.0$	_	B32776E8206+000	14.5	7.8	24.0	1.7	15.9	440
20	$43.0 \times 22.0 \times 41.5$	20.3	B32776T8206K000	14.5	7.2	14.0	1.7	15.1	280
22	$28.0\times37.0\times42.0$	10.2	B32776G8226+000	15.5	6.8	11.0	1.7	15.3	440
22	$28.0\times37.0\times42.0$	_	B32776E8226+000	15.0	7.1	25.0	1.7	16.0	440
25	$28.0\times42.5\times41.5$	10.2	B32776G8256+000	17.0	6.1	11.0	1.7	15.4	440
25	$28.0\times42.5\times41.5$	-	B32776E8256+000	16.5	6.4	28.0	1.8	16.3	440
30	$30.0 \times 45.0 \times 42.0$	20.3	B32776G8306+000	19.5	5.1	12.0	1.7	15.6	400
30	$30.0 \times 45.0 \times 42.0$	-	B32776E8306+000	19.0	5.5	30.0	1.8	16.7	400
35	$33.0\times48.0\times42.0$	20.3	B32776G8356+000	22.0	4.3	14.0	1.7	15.7	180
$V_{R,70}$	$_{\rm C} = 900 \text{ V DC}, V_{\rm op}$	_{85 °C} =	800 V DC						
5	$24.0\times15.0\times41.5$	-	B32776T9505+000	5.5	26.1	19.0	1.5	13.4	1040
7.5	$24.0\times19.0\times41.5$	-	B32776T9755K000	7.5	17.8	18.0	1.5	13.5	780
15	$20.0\times39.5\times41.5$	10.2	B32776G9156K000	12.5	9.1	12.0	1.5	13.6	640
15	$20.0\times39.5\times41.5$	_	B32776E9156K000	12.0	9.4	28.0	1.5	14.1	640
16	$43.0 \times 22.0 \times 41.5$	20.3	B32776T9166K000	14.0	8.1	14.0	1.5	13.5	280
20	$28.0\times37.0\times42.0$	10.2	B32776G9206K000	15.0	7.0	11.0	1.5	13.6	440
20	$28.0\times37.0\times42.0$	-	B32776E9206K000	15.0	7.3	26.0	1.6	14.2	440
22	$28.0\times42.5\times41.5$	10.2	B32776G9226K000	17.0	6.3	12.0	1.5	13.7	440
22	$28.0\times42.5\times41.5$	-	B32776E9226K000	16.5	6.6	29.0	1.6	14.5	440
25	$30.0 \times 45.0 \times 42.0$	20.3	B32776G9256+000	19.0	5.5	13.0	1.5	13.8	400
25	$30.0 \times 45.0 \times 42.0$	-	B32776E9256+000	18.5	5.9	32.0	1.6	14.7	400
30	$33.0\times48.0\times42.0$	20.3	B32776G9306+000	21.5	4.7	14.0	1.5	13.9	180

MOQ = Minimum Order Quantity, consisting of 4 packing units. Intermediate capacitance values are available on request.

Composition of ordering code

- + = Capacitance tolerance code:
 - $J = \pm 5\%$

K = ±10%

1) Capacitance value measured at 1 kHz

2) Max ripple current I_{RMS} at 70 °C, 10 kHz for $\Delta T \le 20$ °C at $\Delta ESR_{typ} \le \pm 5\%$



B32776

MKP DC link – high density series – up to 480 μF

Ordering codes and packing units (lead spacing 37.5 mm)

$C_R^{1)}$	Max. dimensions	P ₁	Ordering code	I _{RMS,max} ²⁾	ESR _{typ}	ESL _{typ} ³⁾	tan δ	tan δ	pcs.
	w × h × l		(composition see	70 °C	70 °C	70 °C			MOQ
			below)	10 kHz	10 kHz	10 kHz	1 kHz	10 kHz	
μF	mm	mm		A	mΩ	nH	10 ⁻³	10 ⁻³	
V_{B70}	° _C = 1100 V DC, V _{op}	₈₅ ° _C =	920 V DC		I		1		
	$24.0 \times 15.0 \times 41.5$	_	B32776T0395+000	5.0	30.5	18.0	1.4	12.1	1040
5	24.0 imes 19.0 imes 41.5	_	B32776T0505+000	6.5	23.6	18.0	1.4	12.1	780
12	$20.0\times39.5\times41.5$	10.2	B32776G0126+000	12.0	10.2	12.0	1.4	12.2	640
12	$20.0\times39.5\times41.5$	_	B32776E0126+000	11.5	10.5	28.0	1.4	12.6	640
13	$43.0 \times 22.0 \times 41.5$	20.3	B32776T0136K000	13.0	8.9	14.0	1.4	12.1	280
14	$28.0\times37.0\times42.0$	10.2	B32776G0146+000	13.5	8.7	21.0	1.4	12.2	440
14	$28.0\times37.0\times42.0$	-	B32776E0146+000	13.5	9.0	25.0	1.4	12.6	440
16	$28.0\times42.5\times41.5$	10.2	B32776G0166+000	15.5	7.4	12.0	1.4	12.3	440
16	$28.0\times42.5\times41.5$	-	B32776E0166+000	15.0	7.8	30.0	1.4	12.9	440
20	$30.0\times45.0\times42.0$	20.3	B32776G0206+000	18.0	6.0	14.0	1.4	12.4	400
20	$30.0 \times 45.0 \times 42.0$	-	B32776E0206+000	17.5	6.5	32.0	1.4	13.1	400
22	$33.0\times48.0\times42.0$	20.3	B32776G0226+000	21.0	4.9	15.0	1.3	11.4	180
$V_{R,70}$	° _C = 1300 V DC, V _{op} ,	_{85 °C} =	1100 V DC						
2.7	$24.0\times15.0\times41.5$	—	B32776T1275+000	5.0	34.7	19.0	1.1	9.6	1040
3.5	$24.0\times19.0\times41.5$	-	B32776T1355+000	6.0	27.4	18.0	1.1	9.7	780
8.0	$20.0\times 39.5\times 41.5$	10.2	B32776G1805+000	11.0	12.1	12.0	1.1	9.7	640
8.0	$20.0\times 39.5\times 41.5$	-	B32776E1805+000	10.5	12.4	24.0	1.2	10.0	640
9.0	$43.0 \times 22.0 \times 41.5$	20.3	B32776T1905K000	12.0	10.7	13.0	1.1	9.7	280
10	$28.0\times37.0\times42.0$	10.2	B32776G1106+000	13.0	9.6	11.0	1.1	9.7	440
10	$28.0\times37.0\times42.0$	-	B32776E1106+000	12.5	9.9	26.0	1.2	10.0	440
12	$28.0\times42.5\times41.5$	10.2	B32776G1126+000	14.5	8.1	12.0	1.1	9.8	440
12	$28.0\times42.5\times41.5$	-	B32776E1126+000	14.0	8.5	28.0	1.2	10.1	440
14	$30.0 \times 45.0 \times 42.0$	20.3	B32776G1146+000	17.0	6.8	14.0	1.1	10.1	400
14	$30.0 \times 45.0 \times 42.0$	—	B32776E1146+000	16.5	7.3	32.0	1.2	10.4	400
16	$33.0\times48.0\times42.0$	20.3	B32776G1166+000	19.0	6.0	15.0	1.1	9.9	180

MOQ = Minimum Order Quantity, consisting of 4 packing units. Intermediate capacitance values are available on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $J = \pm 5\%$ K = $\pm 10\%$

1) Capacitance value measured at 1 kHz

2) Max ripple current I_{RMS} at 70 °C, 10 kHz for $\Delta T \le 20$ °C at $\Delta ESR_{typ} \le \pm 5\%$



B32778

MKP DC link – high density series – up to 480 μF

Ordering codes and packing units (lead spacing 52.5 mm, $P_1 = 20.3$ mm)

C _R ¹⁾	Max. dimensions	Ordering code	I _{RMS.max} ²⁾	ESR _{typ}	ESL _{typ} ³⁾	tan δ	tan δ	pcs.
OR	$w \times h \times l$	(composition see	70 °C	70 °C	70 °C	tan o	ano	MOQ
	WAIIAI	below)	10 kHz	10 kHz	10 kHz	1 kHz	10 kHz	WOQ
μF	mm		A	mΩ	nH	10 ⁻³	10 KHZ	
<u>.</u>			A	11152		10 °	10 °	
V _{R,70}	$v_{\rm C} = 450 \text{ V DC}, V_{\rm op,85}$	$r_{\rm C} = 450 \text{ V DC}$	1	1	1	•	1	-
55	$43.0\times24.0\times57.5$	B32778T4556K000	16.5	7.2	13.0	4.3	41.7	420
75	$30.0\times45.0\times57.5$	B32778G4756+000	21.0	5.6	12.0	4.4	42.6	280
80	$30.0\times45.0\times57.5$	B32778G4806+000	21.5	5.3	13.0	4.4	42.7	280
100	$35.0\times50.0\times57.5$	B32778G4107+000	26.0	4.3	14.0	4.5	43.3	108
110	$35.0\times50.0\times57.5$	B32778G4117K000	27.0	3.9	15.0	4.5	43.6	108
150	$130.0\times24.0\times57.5$	B32778J4157K000	43.5	2.7	4.0	4.4	42.1	80
170	$45.0\times57.0\times57.5$	B32778G4177+000	36.5	2.6	17.0	4.6	45.7	140
180	$60.0\times45.0\times57.5$	B32778G4187+000	39.0	2.5	19.0	4.6	44.6	200
480	$130.0\times58.0\times57.5$	B32778J4487K000	79.5	0.9	6.0	4.8	45.4	40
V _{R,70}	$_{C} = 575 \text{ V DC}, \text{ V}_{op,85}$	_{°c} = 500 V DC						
40	$43.0\times24.0\times57.5$	B32778T5406K000	15.5	8.5	13.0	3.6	34.5	420
60	$30.0\times45.0\times57.5$	B32778G5606+000	20.5	5.8	13.0	3.7	35.3	280
80	$35.0\times50.0\times57.5$	B32778G5806+000	25.5	4.4	15.0	3.7	36.0	108
110	$130.0\times24.0\times57.5$	B32778J5117K000	40.5	3.0	5.0	3.6	34.5	80
120	$45.0\times57.0\times57.5$	B32778G5127+000	34.5	3.1	17.0	3.8	37.2	140
130	$60.0\times45.0\times57.5$	B32778G5137+000	36.5	2.8	19.0	3.8	36.7	200
360	$130.0\times58.0\times57.5$	B32778J5367K000	75.0	1.0	6.0	4.0	37.3	40
V _{R,70}	$_{\rm C} = 800 \text{ V DC}, \text{ V}_{\rm op,85}$	°c = 700 V DC						
30	$43.0\times24.0\times57.5$	B32778T8306K000	14.5	9.8	14.0	3.2	30.2	420
45	$30.0\times45.0\times57.5$	B32778G8456+000	19.5	6.6	14.0	3.2	30.9	280
50	$30.0\times45.0\times57.5$	B32778G8506+000	20.0	6.3	13.0	3.2	30.9	280
55	$35.0\times50.0\times57.5$	B32778G8556+000	23.0	5.6	14.0	3.2	31.1	108
60	$35.0\times50.0\times57.5$	B32778G8606+000	23.5	5.1	15.0	3.3	31.2	108
80	$130.0\times24.0\times57.5$	B32778J8806K000	37.5	3.6	4.0	3.2	30.2	80
90	$45.0 \times 57.0 \times 57.5$	B32778G8906+000	32.5	3.5	17.0	3.3	32.2	140
100	$60.0\times45.0\times57.5$	B32778G8107+000	34.5	3.2	19.0	3.3	31.9	200
270	$130.0\times58.0\times57.5$	B32778J8277K000	70.5	1.2	6.0	3.5	32.4	40

MOQ = Minimum Order Quantity, consisting of 4 packing units. Intermediate capacitance values are available on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $J = \pm 5\%$ K = $\pm 10\%$

1) Capacitance value measured at 1 kHz

2) Max ripple current I_{RMS} at 70 °C, 10 kHz for $\Delta T \le 20$ °C at $\Delta ESR_{typ} \le \pm 5\%$



B32778

MKP DC link – high density series – up to 480 μF

Ordering codes and packing units (lead spacing 52.5 mm, P₁ = 20.3 mm)

$C_{R}^{1)}$	Max. dimensions	Ordering code	I _{RMS,max} ²⁾	ESR _{typ}	ESL _{typ} ³⁾	tan δ	tan δ	pcs.
	$w \times h \times l$	(composition see	70 °C	70 °C	70 °Ĉ			MOQ
		below)	10 kHz	10 kHz	10 kHz	1 kHz	10 kHz	
μF	mm		Α	mΩ	nH	10 ⁻³	10 ⁻³	
V _{R,70}	_{°c} = 900 V DC, V _{op,85}	_{°c} = 800 V DC						
25	$43.0 \times 24.0 \times 57.5$	B32778T9256K000	13.5	10.7	13.0	2.8	26.8	420
35	$30.0\times45.0\times57.5$	B32778G9356+000	18.0	7.7	13.0	2.9	27.3	280
50	$35.0\times50.0\times57.5$	B32778G9506K000	22.5	5.6	15.0	2.9	27.7	108
70	$45.0\times57.0\times57.5$	B32778G9706+000	31.0	3.8	18.0	3.0	28.5	140
70	$130.0\times24.0\times57.5$	B32778J9706K000	36.0	3.8	4.0	2.9	27.2	80
75	$60.0\times45.0\times57.5$	B32778G9756+000	32.5	3.6	20.0	2.9	28.2	200
210	$130.0\times58.0\times57.5$	B32778J9217K000	66.0	1.3	6.0	3.1	28.6	40
V _{R,70}	_{°C} = 1100 V DC, V _{op,85}	_{°c} = 920 V DC						
20	$43.0\times24.0\times57.5$	B32778T0206K000	13.0	11.9	13.0	2.6	24.1	420
30	$30.0\times45.0\times57.5$	B32778G0306+000	17.5	8.2	13.0	2.6	24.5	280
40	$35.0\times50.0\times57.5$	B32778G0406+000	21.5	6.2	15.0	2.7	25.9	108
58	$45.0\times57.0\times57.5$	B32778G0586+000	29.0	4.3	17.0	2.7	25.4	140
60	$60.0\times45.0\times57.5$	B32778G0606+000	30.5	4.0	19.0	2.7	25.2	200
60	$130.0\times24.0\times57.5$	B32778J0606K000	34.5	4.1	4.0	2.7	25.1	80
200	$130.0\times58.0\times57.5$	B32778J0207K000	66.0	1.4	6.0	3.0	26.8	40
V _{R,70}	$_{\rm C} = 1300 \text{ V DC}, \text{ V}_{\rm op,85}$	_{°c} = 1100 V DC						
14	$43.0\times24.0\times57.5$	B32778T1146K000	12.0	13.8	13.0	2.1	19.5	420
20	$30.0\times45.0\times57.5$	B32778G1206+000	16.0	9.7	13.0	2.1	19.8	280
25	$35.0\times50.0\times57.5$	B32778G1256+000	19.0	7.8	15.0	2.1	19.9	108
27	$35.0\times50.0\times57.5$	B32778G1276+000	19.5	7.3	15.0	2.1	20.0	108
38	$130.0\times24.0\times57.5$	B32778J1386K000	31.5	5.1	4.0	2.1	19.5	80
40	$45.0\times57.0\times57.5$	B32778G1406+000	26.5	5.0	17.0	2.2	20.3	140
42	$60.0\times45.0\times57.5$	B32778G1426+000	28.0	4.7	19.0	2.2	20.2	200
120	$130.0\times58.0\times57.5$	B32778J1127K000	58.5	1.7	6.0	2.3	20.5	40

MOQ = Minimum Order Quantity, consisting of 4 packing units. Intermediate capacitance values are available on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $J = \pm 5\%$ K = $\pm 10\%$

1) Capacitance value measured at 1 kHz

2) Max ripple current I_{RMS} at 70 °C, 10 kHz for $\Delta T \le 20$ °C at $\Delta ESR_{typ} \le \pm 5\%$



MKP

B32774 ... B32778

MKP DC link – high density series up to 480 μF

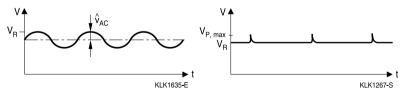
Technical data

Reference standard: IEC 61071.

All data given at T = 20 °C, unless otherwise specified.

Operating temperature range (case)	Max. ope	erating ter	nperature	, T _{op.max}	+105 °C	;	
opolaling compolatero rango (caso)	•	0	, mperature	· • • • • • • • • • • • • • • • • • • •	+105 °C	;	
	Lower ca	ategory te	mperature	e T _{min}	_40 °C	;	
Insulation Resistance R _{ins}	τ > 10 00	00 s (after	1 min.)				
given as time constant	For $V_R \ge$	500 V me	easured at	t 500 V			
$\tau = C_R \cdot R_{ins}$, rel. humidity $\leq 65\%$	For $V_R <$	500 V me	easured a	t V _R			
(minimum as-delivered values)							
DC test voltage between terminals (10 s)	$1.5 \cdot V_{R}$						
Voltage test terminal to case (10 s)	2110 V A	AC, 50 Hz					
Pulse Handling Capability (V/µs)	I _P (A) / C (μF)						
Reliability: Failure rate λ	10 fit (≤ ⁻	1 · 10 ⁻⁹ /h)	at 0.5 · V	′ _R , 40 °C			
	For conversion to other operating conditions and						
	temperatures, refer to chapter "Quality, 2 Reliability".						
Service life t_{SL}	100 000 h at V_{B} and 70 °C						
V _R (V DC)	450	575	800	900	1100	1300	
Continuous operation voltage	450	575	800	900	1100	1300	
V _{op} (V DC) at 70 °C							
Continuous operation voltage	450	500	700	800	920	1100	
V _{op} (V DC) at 85 °C							
For temperatures between	1.33%/°C of V _{op} derating compared to V _{op} at 85 °C						
85 °C and 105 °C			U				

Typical waveforms



Restrictions:

 $\bm{V}_{R}\!\!:\!$ Maximum operating peak voltage of either polarity but of a non-reversing waveform, for which the capacitor has been designed for continuous operation.

 $\hat{v}_{\text{AC}} \leq \boldsymbol{0.2} \, \cdot \, \boldsymbol{V}_{\text{R}}$





B32774 ... B32778

MKP DC link – high density series up to 480 μ F

Overvoltage	Maximum duration within one day	Observation
1.1 · V _B	30% of on-load duration	System regulation
1.15 · V _R	30 min.	System regulation
1.2 · V _B	5 min.	System regulation
1.3 · V _R	1 min.	System regulation

NOTE 1 An overvoltage equal to $1.5 \cdot V_R$ for 30 ms is permitted 1000 times during the life of the capacitor.

The amplitudes of the overvoltages that may be tolerated without significant reduction in the life time of the capacitor depend on their duration, the number of application and the capacitor temperature.

In addition these values assume that the overvoltages may appear when the internal temperature of the capacitor is less than 0 °C but within the temperature category.

NOTE 2 The average applied voltage must not be higher than the specified voltage.

Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in $V/\mu s$.

Note:

The values of dV/dt provided below must not be exceeded in order to avoid damaging the capacitor.

dV/dt values

Lead spacing	27.5 mm			37.5 mm						
Туре	B32774			B32776						
V _R (V DC)	450	800	1100	1300	450	575	800	900	1100	1300
dV/dt in V/µs	30	40	75	100	21	22	22	35	54	73

Lead spacing	52.5 mm					
Туре	B32778					
V _R (V DC)	450	575	800	900	1100	1300
dV/dt in V/µs	14	14	15	22	35	50



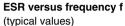


Additional technical information can be found under "Design support" on www.epcos.com

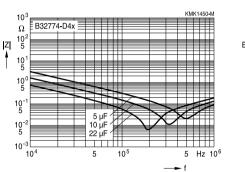
Impedance Z versus frequency f

(typical values)

Lead spacing 27.5 mm / B32774D4*



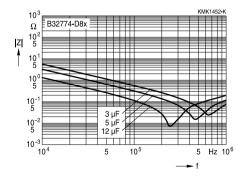
Lead spacing 27.5 mm / B32774D4*



KMK1451- 10^{2} B32774-D4x mΩ 5 ESB 5 µF 10 µF 10¹ 22 µF 5 10⁰ 10³ 10^{2} 10⁴ 5 5 Hz 10⁵ ► f

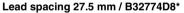
Impedance Z versus frequency f (typical values)

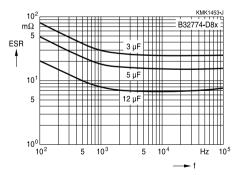
Lead spacing 27.5 mm / B32774D8*



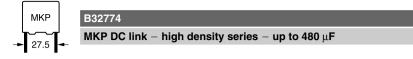
ESR versus frequency f

(typical values)



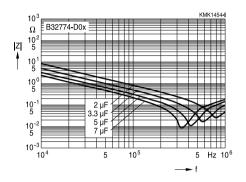






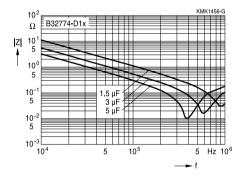
Impedance Z versus frequency f (typical values)

Lead spacing 27.5 mm / B32774D0*



Impedance Z versus frequency f (typical values)

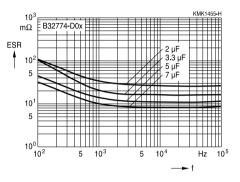
Lead spacing 27.5 mm / B32774D1*



ESR versus frequency f

(typical values)

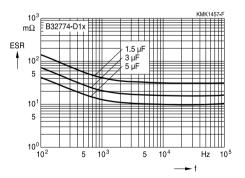
Lead spacing 27.5 mm / B32774D0*



ESR versus frequency f

(typical values)

Lead spacing 27.5 mm / B32774D1*





37.5

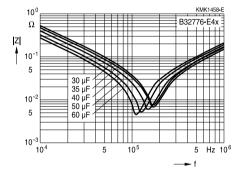


MKP DC link – high density series – up to 480 μF

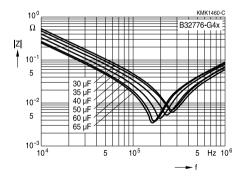
Characteristics curves

Impedance Z versus frequency f (typical values)

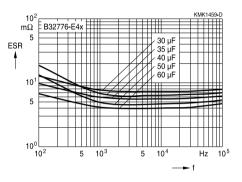
Lead spacing 37.5 mm / B32776-E4x



Impedance Z versus frequency f (typical values) Lead spacing 37.5 mm / B32776-G4x

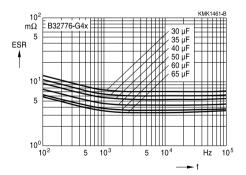


ESR versus frequency f (typical values) Lead spacing 37.5 mm / B32776-E4x

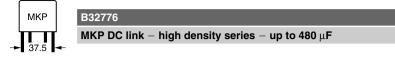


ESR versus frequency f (typical values)

Lead spacing 37.5 mm / B32776-G4x

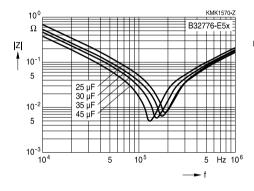




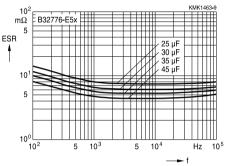


Impedance Z versus frequency f (typical values)

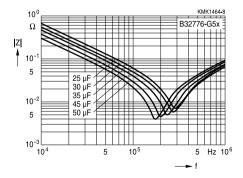
Lead spacing 37.5 mm / B32776-E5x



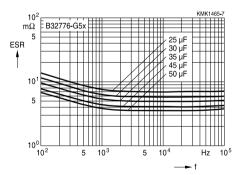
ESR versus frequency f (typical values) Lead spacing 37.5 mm / B32776-E5x



Impedance Z versus frequency f (typical values) Lead spacing 37.5 mm / B32776-G5x



ESR versus frequency f (typical values) Lead spacing 37.5 mm / B32776-G5x





37.5

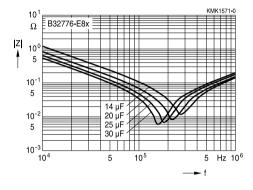


MKP DC link – high density series – up to 480 μF

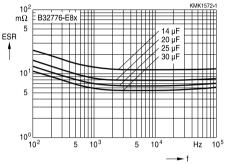
Characteristics curves

Impedance Z versus frequency f (typical values)

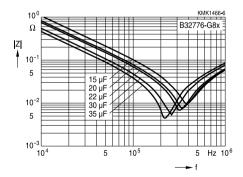
Lead spacing 37.5 mm / B32776-E8x



ESR versus frequency f (typical values) Lead spacing 37.5 mm / B32776-E8x



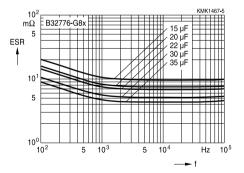
Impedance Z versus frequency f (typical values) Lead spacing 37.5 mm / B32776-G8x



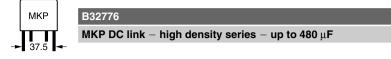
ESR versus frequency f

(typical values)

Lead spacing 37.5 mm / B32776-G8x

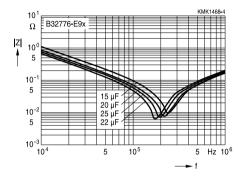




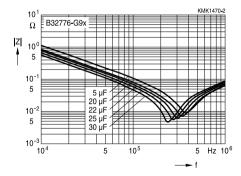


Impedance Z versus frequency f (typical values)

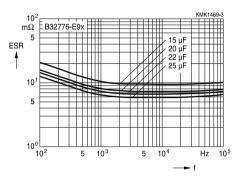
Lead spacing 37.5 mm / B32776-E9x



Impedance Z versus frequency f (typical values) Lead spacing 37.5 mm / B32776-G9x

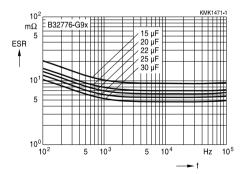


ESR versus frequency f (typical values) Lead spacing 37.5 mm / B32776-E9x



ESR versus frequency f (typical values)

Lead spacing 37.5 mm / B32776-G9x





37.5

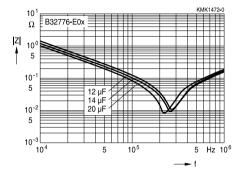


MKP DC link – high density series – up to 480 μF

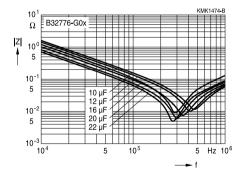
Characteristics curves

Impedance Z versus frequency f (typical values)

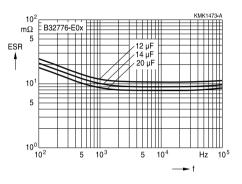
Lead spacing 37.5 mm / B32776-E0x



Impedance Z versus frequency f (typical values) Lead spacing 37.5 mm / B32776-G0x

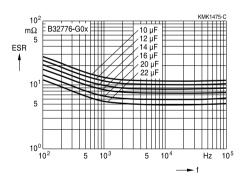


ESR versus frequency f (typical values) Lead spacing 37.5 mm / B32776-E0x



ESR versus frequency f (typical values)

Lead spacing 37.5 mm / B32776-G0x



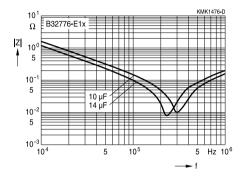
Please read *Cautions and warnings* and *Important notes* at the end of this document.



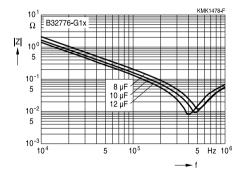


Impedance Z versus frequency f (typical values)

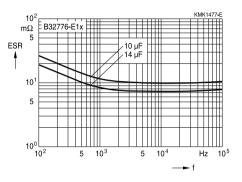
Lead spacing 37.5 mm / B32776-E1x



Impedance Z versus frequency f (typical values) Lead spacing 37.5 mm / B32776-G1x

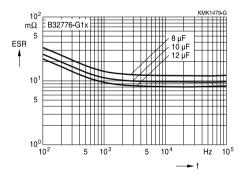


ESR versus frequency f (typical values) Lead spacing 37.5 mm / B32776-E1x



ESR versus frequency f (typical values)

Lead spacing 37.5 mm / B32776-G1x







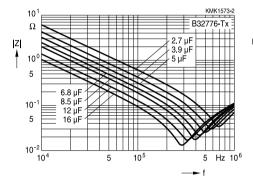
MKP DC link – high density series – up to 480 μF

Characteristics curves

Impedance Z versus frequency f

(typical values)

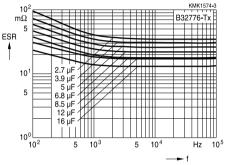
Lead spacing 37.5 mm / B32776-Tx / 2-pins



ESR versus frequency f (typical values)

Lead spacing 37.5 mm / B32776-Tx / 2-pins

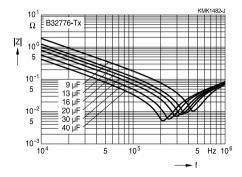
B32776



Impedance Z versus frequency f

(typical values)

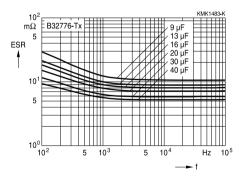
Lead spacing 37.5 mm / B32776-Tx / 4-pins



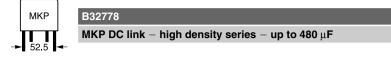
ESR versus frequency f

(typical values)

Lead spacing 37.5 mm / B32776-Tx / 4-pins

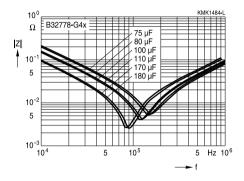




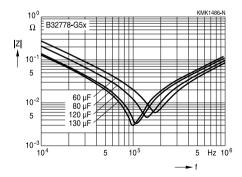


Impedance Z versus frequency f (typical values)

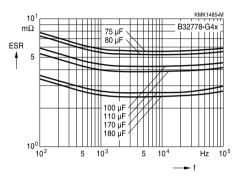
Lead spacing 52.5 mm / B32778-G4x



Impedance Z versus frequency f (typical values) Lead spacing 52.5 mm / B32778-G5x

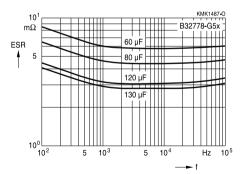


ESR versus frequency f (typical values) Lead spacing 52.5 mm / B32778-G4x



ESR versus frequency f (typical values)

Lead spacing 52.5 mm / B32778-G5x





52.5

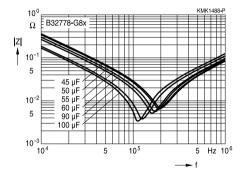


MKP DC link – high density series – up to 480 μF

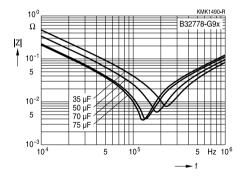
Characteristics curves

Impedance Z versus frequency f (typical values)

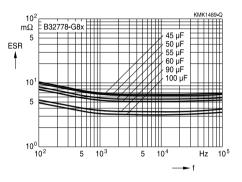
Lead spacing 52.5 mm / B32778-G8x



Impedance Z versus frequency f (typical values) Lead spacing 52.5 mm / B32778-G9x

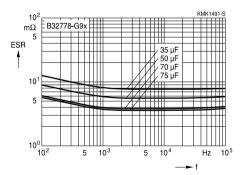


ESR versus frequency f (typical values) Lead spacing 52.5 mm / B32778-G8x

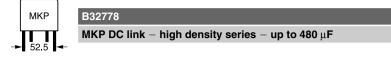


ESR versus frequency f (typical values)

Lead spacing 52.5 mm / B32778-G9x

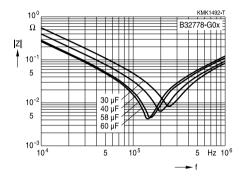




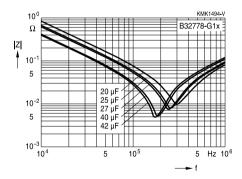


Impedance Z versus frequency f (typical values)

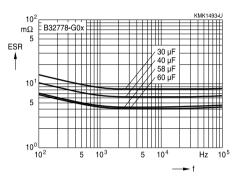
Lead spacing 52.5 mm / B32778-G0x



Impedance Z versus frequency f (typical values) Lead spacing 52.5 mm / B32778-G1x

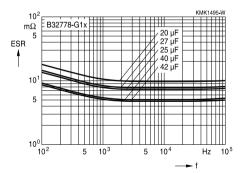


ESR versus frequency f (typical values) Lead spacing 52.5 mm / B32778-G0x



ESR versus frequency f (typical values)

Lead spacing 52.5 mm / B32778-G1x





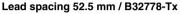
52.5

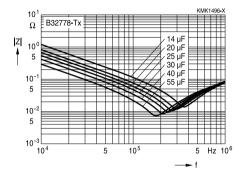


MKP DC link – high density series – up to 480 μF

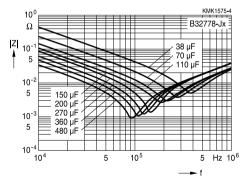
Characteristics curves

Impedance Z versus frequency f (typical values)

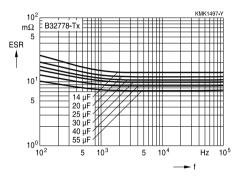




Impedance Z versus frequency f (typical values) Lead spacing 52.5 mm / B32778-Jx



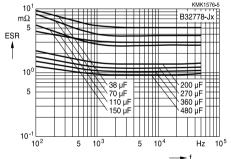
ESR versus frequency f (typical values) Lead spacing 52.5 mm / B32778-Tx



ESR versus frequency f

(typical values)

Lead spacing 52.5 mm / B32778-Jx



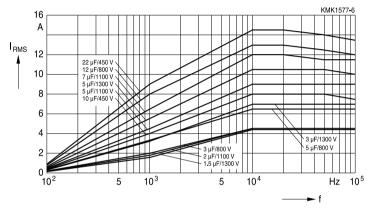




Permissible current I_{RMS} versus frequency f at 70 °C

Lead spacing 27.5 mm

B32774-Dx



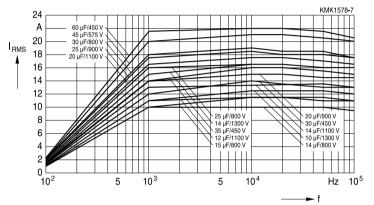




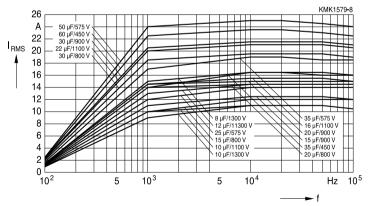
Permissible current I_{RMS} versus frequency f at 70 °C

Lead spacing 37.5 mm

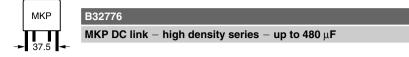
B32776-Ex



B32776-Gx



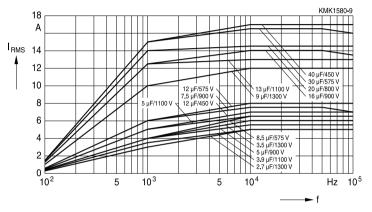




Permissible current I_{RMS} versus frequency f at 70 °C

Lead spacing 37.5 mm

B32776-Tx







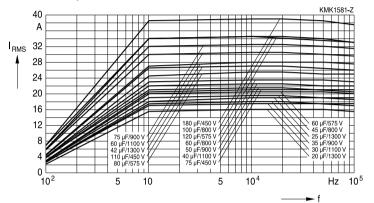
MKP DC link – high density series – up to 480 μF

Characteristics curves

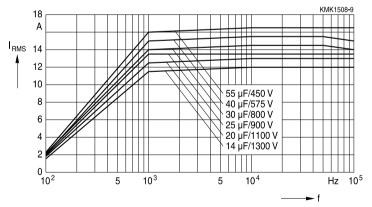
Permissible current I_{RMS} versus frequency f at 70 $^{\circ}$ C

Lead spacing 52.5 mm

B32778-Gx, 4 pins



B32778-Tx, 4 pins



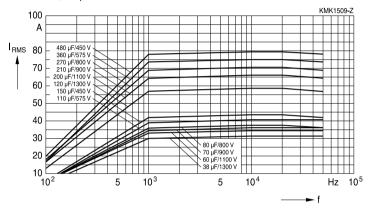




Permissible current I_{RMS} versus frequency f at 70 $^{\circ}$ C

Lead spacing 52.5 mm

B32778-Jx, 12 pins



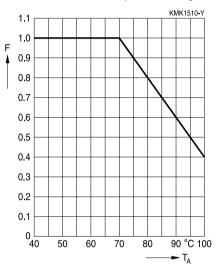




B32774 ... B32778

MKP DC link – high density series up to 480 μF

Curves Characteristics (Irms derating vs temperature)



Maximum I_{RMS} current as function of the ambient temperature: I_{RMS} (T_A) = Factor × I_{RMS} (70 °C)

B32774 ... B32778

MKP DC link – high density series up to 480 μF

Heat transference for self heating calculation

KMK1535-9

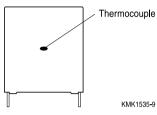


Figure 1

Box dimer	nsions	Equivalent heat coefficient		
w (mm)	h (mm)	l (mm)	G (mW/°C)	
11.0	19.0	31.5	25	
11.0	21.0	31.5	28	
12.5	21.5	31.5	30	
13.5	23.0	31.5	32	
14.0	24.5	31.5	35	
15.0	24.5	31.5	36	
16.0	32.0	31.5	45	
18.0	27.5	31.5	44	
18.0	33.0	31.5	48	
19.0	30.0	31.5	48	
20.0	11.0	31.5	65	
21.0	31.0	31.5	51	
22.0	36.5	31.5	58	
12.0	22.0	41.5	70	
14.0	25.0	41.5	43	
16.0	28.5	41.5	50	
18.0	32.5	41.5	59	
20.0	39.5	41.5	72	
24.0	19.0	41.5	50	
24.0	15.0	41.5	44	
28.0	37.0	42.0	83	
28.0	42.5	41.5	90	
30.0	45.0	42.0	100	
33.0	48.0	42.0	100	
43.0	22.0	41.5	80	
30.0	45.0	57.5	125	
35.0	50.0	57.5	145	
43.0	24.0	57.5	103	
45.0	57.0	57.5	185	
60.0	45.0	57.5	192	
130.0	24.0	57.5	200	
130.0	58.0	57.5	300	

The equivalent heat coefficient "G (mW/ºC)" is given for measuring the temperature on the lateral surface of the plastic box as figure1 shows. By using a thermocouple and avoiding effect of radiation and convection the temperature measured during operation conditions should be a result of the dissipated power divided by the equivalent heat coefficient.



B32774 ... B32778

MKP DC link – high density series up to 480 μF

Self Heating by power dissipation & equivalent heat coefficient

The I_{RMS} and consequently the power dissipation must be limited during operation in order to not exceed the maximum limit of ΔT allowed for this series. ΔT_{max} given for this series is equal or lower than 20 °C at rated temperature (70 °C), for higher ambient temperatures ΔT_{max} (T) will have the same derating factor than I_{RMS} vs temperature and then an equivalent derating as per: ambient temperatures ΔT_{max} (T) will have the same derating factor than I_{RMS} vs temperature and then an equivalent derating as per:

$$\Delta T_{max}$$
 (T) = (Factor)² × ΔT (70 °C).

For any particular I_{RMS} the ΔT may be calculated by:

 $\Delta T (^{\circ}C) = P_{dis} (mW) / G(mW/^{\circ}C).$

Where ΔT (°C) is the difference between the temperature measured on the box (see figure 1) and the ambient temperature when capacitor is working during normal operation;

$$\Delta T (^{\circ}C) = T_{op} (^{\circ}C) - T_{A} (^{\circ}C)$$

It represents the increasing of temperature provoked by the I_{RMS} during operation. G (mW/°C) is the equivalent heat coefficient described above and P_{dis} (mW) is the dissipated power defined by:

 P_{dis} (mW) = ESR_{typ} (m Ω) × I_{rms}^2 (A_{RMS}).

Example for thermal calculation:

We will take as reference B32778G0306K (30 μ F/1100 V) type for thermal calculation. Considering the following load and capacitor characteristics:

 I_{RMS} : 12 A_{\text{RMS}} at 20 kHz T_{A} : 85 °C $30 \times 45 \times 57.5$ box G (mW/°C): 125

Then we have to find the ESR_{typ} at 20 kHz what is approx . 8.2 m Ω . So according to:

we have the following:

 P_{dis} (mW) = 8.2 m $\Omega \times 12 A_{BMS}^2$ = 1181 mW

 P_{dis} (mW) = ESR_{tvp} (m Ω) × I_{rms}^{2} (A_{RMS})

and as per:

 $\Delta T (^{\circ}C) = P_{dis} (mW) / G (mW/^{\circ}C)$

we have the following:

 ΔT (°C) = 1181 (mW) / 125 (mW/°C) = 9.5 °C.

What is below of the

 ΔT_{max} (85 °C) = (Factor)² × ΔT (70 °C) = (0.7)² × 20 °C = 9.8 °C.

On the other hand we may confirm that max I_{RMS} at 20 kHz at 70 °C = 17.5 A_{RMS}

And then max I_{RMS} for 85 °C of ambient temperature is defined as follows:

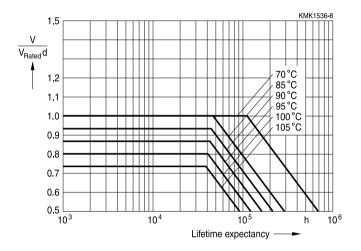
 I_{RMS} (85 °C) = Factor × I_{RMS} (70 °C) = 0.7 × 17.5 A_{RMS} = 12.25 A_{RMS} .

What confirms once again that I_{RMS} (12 A_{RMS} at 20 kHz) is below the max specified for such frequency and ambient temperature.

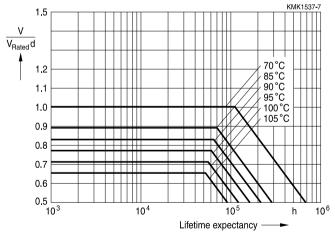




Life time expectancy - typical curve (450 V DC / B3277x-X4



Life time expectancy - typical curve (575 V DC / 800 V DC / 900 V DC / 1100 V DC / 1300 V DC / B3277X-5/8/9/0/1)



Note: Confidence level of 95%



MKP DC link – high density series up to 480 μF

MKP

Testing and Standards

Test	Reference	Conditions of test		Performance requirements
Electrical Parameters (Routine test)	IEC 61071-11	Voltage between terminals, 1.5 V _R , during 10 s Insulation resistance, R _{INS} at V _R if V _R < 500 V or 500 V if V _R \ge 500 V		Within specified limits
		Capacitance, C at 1 kHz (room temperature) Dissipation factor, tan δ at 1/10 kHz (room temperature)		
Robustness of termina- tions (Type test)	IEC 60068-2-21	Tensile strength (test Ua1)TensileWire diameterforce $0.5 < d_1 \le 0.8 \text{ mm}$ 10 N $0.8 < d_1 \le 1.25 \text{ mm}$ 20 N		Capacitance and tan δ within specified limits
Resistance to soldering heat (Type test)	IEC 60068-2-20, test Tb, method 1A	Solder bath temperature at 260 ± 5 °C, immersion for 10 seconds		$\Delta C/C_0 \le 2\%$ $\Delta \tan \delta$ ≤ 0.002
Rapid change of temperature (Type test)	IEC 60384-16	T_A = lower category temperature T_B = upper category temperature Five cycles, duration t = 30 min.		$\begin{split} & \Delta C/C_0 \leq 2\% \\ & \Delta \ tan \ \delta \leq 0.002 \\ &R_{\text{INS}} \geq 50\% \ \text{of initial limit} \end{split}$
Vibration (Type test)	IEC 60384-16	Test F _c : vibration sinusoidal Displacement: 0.75 mm Accleration: 98 m/s ² Frequency: 10 Hz 500 Hz Test duration: 3 orthogonal axes, 2 hours each axe		No visible damage
Bump (Type test)	IEC 60384-16	Test Eb: Total 4000 bumps with 390 m/s ² mounted on PCB 6 ms duration		No visible damage $ \Delta C/C_0 \le 2\%$ $ \Delta \tan \delta \le 0.002$ $R_{INS} \ge 50\%$ of initial limit
Climatic sequence (Type test)	IEC 60384-16	Dry heat Tb / 16 h. Damp heat cyclic, 1st cycle + 55 °C / 24h / 95% 100% RH Cold Ta / 2h Damp heat cyclic, 5 cycles + 55 °C / 24h / 95% 100% RH		No visible damage $ \Delta C/C_0 \le 3\%$ $ \Delta \tan \delta \le 0.001$ $R_{INS} \ge 50\%$ of initial limit





MKP DC link – high density series up to 480 μF

Test	Reference	Conditions of test	Performance requirements
Damp Heat	IEC 60384-16	Test Ca	No visible damage
Steady State		40 °C / 93% RH / 56 days	$ \Delta C/C_0 \le 5\%$
(Type test)			$ \Delta \tan \delta \le 0.005$
, ,			$R_{INS} \ge 50\%$ of initial limit
Endurance	IEC 60384-16	70 °C / 1.25 V _R / 1000 hours or	No visible damage
(Type test)		85 °C / 1.25 V _{op} / 1000 hours or	$ \Delta C/C_0 \le 5\%$ at 1 kHz
		100 °C / 1.25 V _{op} / 1000 hours	l∆ tan δl ≤ 0.005
			$R_{INS} \ge 50\%$ of initial limit

Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 + 0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder



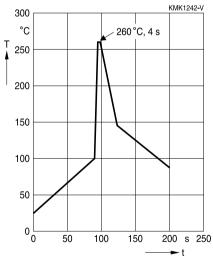


MKP DC link – high density series up to 480 μF

1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A. Conditions:

Series		Solder bath temperature	Soldering time
MKT	boxed (except $2.5 \times 6.5 \times 7.2$ mm) coated uncoated (lead spacing > 10 mm)	260 ±5 °C	10 ±1 s
MFP MKP	(lead spacing > 7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5±1 s
MKP MKT	(lead spacing \leq 7.5 mm) uncoated (lead spacing \leq 10 mm) insulated (B32559)		< 4 s recommended soldering profile for MKT uncoated (lead spacing \leq 10 mm) and insulated (B32559)



Immersion depth	2.0 + 0/-0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 \pm 0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
tan δ	As specified in sectional specification

Please read *Cautions and warnings* and *Important notes* at the end of this document.





MKP DC link – high density series up to 480 μ F

1.3 General notes on soldering

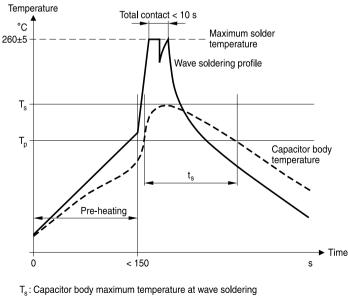
Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics: diameter length thermel r
 - diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommendations

As a reference, the recommended wave soldering profile for our film capacitors is as follows:



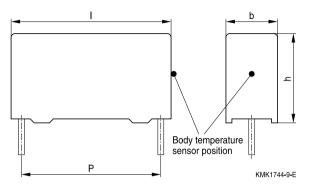
T_n: Capacitor body maximum temperature at pre-heating

KMK1745-A-E





MKP DC link – high density series up to 480 μF



Body temperature should follow the description below:

- MKP capacitor During pre-heating: T_p ≤ 110 °C During soldering: T_s ≤ 120 °C, t_s ≤ 45 s
- MKT capacitor During pre-heating: $T_p \le 125 \text{ °C}$ During soldering: $T_s \le 160 \text{ °C}$, $t_s \le 45 \text{ s}$

When SMD components are used together with leaded ones, the film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.

Leaded film capacitors are not suitable for reflow soldering.

In order to ensure proper conditions for manual or selective soldering, the body temperature of the capacitor (T_s) must be \leq 120 °C.

One recommended condition for manual soldering is that the tip of the soldering iron should be < 360 °C and the soldering contact time should be no longer than 3 seconds.

For uncoated MKT capacitors with lead spacings \leq 10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering

Please refer to EPCOS Film Capacitor Data Book in case more details are needed.



B32774 ... B32778

MKP DC link – high density series up to 480 μF

Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Торіс	Safety information	Reference chapter "General technical
		information"
Storage	Make sure that capacitors are stored within the specified	4.5
conditions	range of time, temperature and humidity conditions.	"Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive	5.3
	flammability), avoid overload of the capacitors (active	"Flammability"
	flammability) and consider the flammability of materials.	
Resistance to	Do not exceed the tested ability to withstand vibration.	5.2
vibration	The capacitors are tested to IEC 60068-2-6.	"Resistance to
	EPCOS offers film capacitors specially designed for	vibration"
	operation under more severe vibration regimes such as	
	those found in automotive applications. Consult our	
	catalog "Film Capacitors for Automotive Electronics".	

Торіс	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"



B32774 ... B32778

MKP DC link – high density series up to 480 μF

Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products.

Detailed information can be found on the Internet under www.epcos.com/orderingcodes.



B32774 ... B32778

MKP DC link – high density series up to 480 μF

Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
α_{c}	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
А	Capacitor surface area	Kondensatoroberfläche
βc	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
C _R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative	Relative Kapazitätsänderung (relative
	deviation of actual value)	Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation	Kapazitätstoleranz (relative Abweichung
	from rated capacitance)	vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔT	Absolute temperature change	Absolute Temperaturänderung
	(self-heating)	(Selbsterwärmung)
∆tan δ	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate	Differentielle Spannungsänderung
	of voltage rise)	(Spannungsflankensteilheit)
$\Delta V / \Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f ₁	Frequency limit for reducing permissible	Grenzfrequenz für thermisch bedingte
	AC voltage due to thermal limits	Reduzierung der zulässigen
		Wechselspannung
f ₂	Frequency limit for reducing permissible	Grenzfrequenz für strombedingte
	AC voltage due to current limit	Reduzierung der zulässigen Wechselspannung
4	Personant frequency	Resonanzfrequenz
f _r ⊏	Resonant frequency Thermal acceleration factor for diffusion	
F _D		Therm. Beschleunigungsfaktor zur Diffusion
F⊤	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I _c	Category current (max. continuous	Kategoriestrom (max. Dauerstrom)
-	current)	- , , , ,



MKP

MKP DC link – high density series up to 480 μF

Symbol	English	German
I _{RMS}	(Sinusoidal) alternating current,	(Sinusförmiger) Wechselstrom
	root-mean-square value	
İ _z	Capacitance drift	Inkonstanz der Kapazität
k ₀	Pulse characteristic	Impulskennwert
Ls	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λο	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P _{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
Ri	Internal resistance	Innenwiderstand
R _{ins}	Insulation resistance	Isolationswiderstand
R₽	Parallel resistance	Parallelwiderstand
Rs	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
$tan \delta_{\scriptscriptstyle D}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ _P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ _s	Series component of dissipation factor	Serienanteil des Verlustfaktors
T _A	Temperature of the air surrounding the component	Temperatur der Luft, die das Bauteil umgibt
T _{max}	Upper category temperature	Obere Kategorietemperatur
T _{min}	Lower category temperature	Untere Kategorietemperatur
toL	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
	and voltage	-spannung
Top	Operating temperature, $T_A + \Delta T$	Beriebstemperatur, $T_A + \Delta T$
T _B	Rated temperature	Nenntemperatur
T _{ref}	Reference temperature	Referenztemperatur
t _{SL}	Reference service life	Referenz-Lebensdauer



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MKP DC link – high density series up to 480 μF

Symbol	English	German
V _{AC}	AC voltage	Wechselspannung
Vc	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V _{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
Vi	Input voltage	Eingangsspannung
Vo	Output voltage	Ausgangssspannung
V _{op}	Operating voltage	Betriebsspannung
V _p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V _R	Rated voltage	Nennspannung
ν _R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V _{RMS}	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
V _{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung
		"Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß



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